

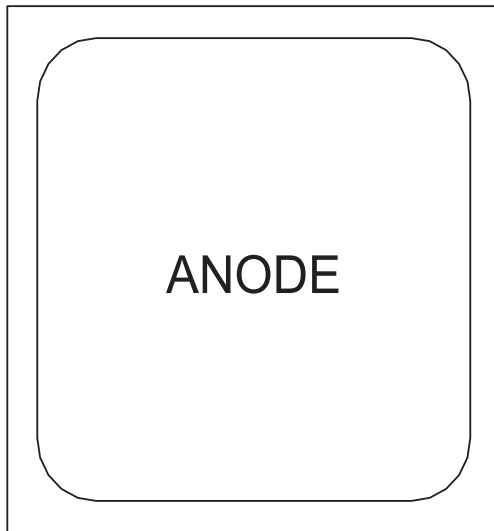
**PROCESS CPD16**  
**Ultra Fast Rectifier**  
1.0 Amp Glass Passivated Rectifier Chip

**Central**<sup>TM</sup>  
**Semiconductor Corp.**

**PROCESS DETAILS**

Process	GLASS PASSIVATED MESA
Die Size	50 x 50 MILS
Die Thickness	12.2 MILS
Anode Bonding Pad Area	34 x 34 MILS
Top Side Metalization	Au - 5,000Å
Back Side Metalization	Au - 2,000Å

**GEOMETRY**



BACKSIDE CATHODE

R0

**GROSS DIE PER 4 INCH WAFER**

4,520

**PRINCIPAL DEVICE TYPES**

UES1001 thru UES1003

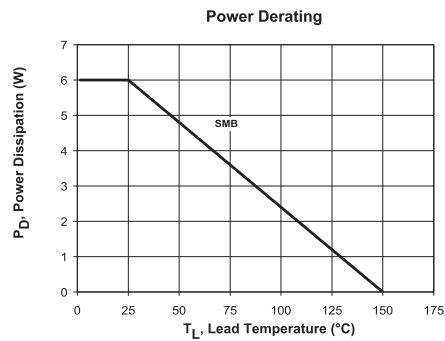
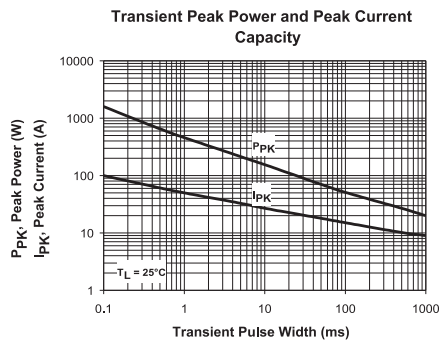
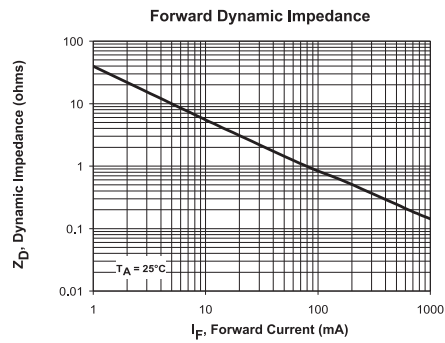
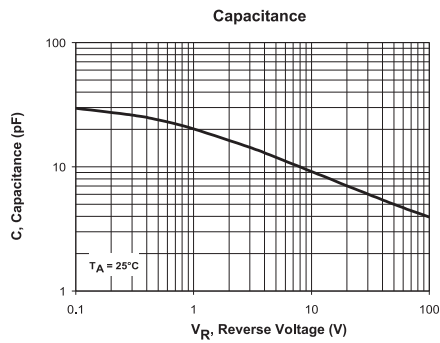
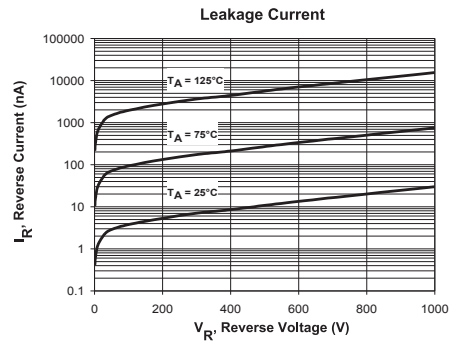
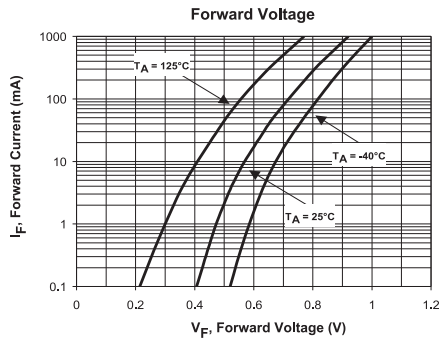
UF4001 thru UF4007

CMR1U-01 Series

CMR1U-01M Series

145 Adams Avenue  
Hauppauge, NY 11788 USA  
Tel: (631) 435-1110  
Fax: (631) 435-1824  
www.centalsemi.com

R2 (19-September 2003)



145 Adams Avenue  
Hauppauge, NY 11788 USA  
Tel: (631) 435-1110  
Fax: (631) 435-1824  
www.centalsemi.com

R2 (19-September 2003)